

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/20/2022

Details for "BQ24008PWP"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
BQ24008PWP	NIPDAU	Level-2-260C-1 YEAR	TI TAIWAN A/T	PWP 20	4.4x6.5x1.15	75.2

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.083519	99.990422	999904	0.111071	1111
Not Categorized	Proprietary Materials		0.000007	0.008381	84	0.000009	0
Precious Metals	Silver	7440-22-4	0.000001	0.001197	12	0.000001	0
Sub-Total			0.083527	100	1000000	0.111082	1111
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.6774	70.000021	700000	0.900867	9009
Thermoplastics	Epoxy	85954-11-6	0.290314	29.999979	300000	0.386085	3861
Sub-Total			0.967714	100	1000000	1.286953	12870
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	27.85926	97.41	974100	37.049732	370497
Copper and Its Alloys	Iron	7439-89-6	0.6864	2.4	24000	0.912836	9128
Copper and Its Alloys	Phosphorus	7723-14-0	0.00858	0.03	300	0.01141	114
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.00858	0.03	300	0.01141	114
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.00858	0.03	300	0.01141	114
Zinc and Its Alloys	Zinc	7440-66-6	0.0286	0.1	1000	0.038035	380
Sub-Total			28.6	100	1000000	38.034834	380348
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.437552	95.12	951200	0.581896	5819
Precious Metals	Gold	7440-57-5	0.003588	0.78	7800	0.004772	48
Precious Metals	Palladium	7440-05-3	0.01886	4.1	41000	0.025082	251
Sub-Total			0.46	100	1000000	0.611749	6117
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	34.914359	84.999999	850000	46.432233	464322
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	0.492909	1.200001	12000	0.655514	6555
Other Plastics and Rubber	Carbon Black	1333-86-4	0.123227	0.3	3000	0.163878	1639
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.123227	0.3	3000	0.163878	1639
Other Plastics and Rubber	Silicone	218163-11-2	1.232272	3.000001	30000	1.638785	16388
Thermoplastics	Epoxy	85954-11-6	4.189723	10.2	102000	5.571868	55719
Sub-Total			41.075717	100	1000000	54.626157	546262
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.00727	100	1000000	5.329226	53292
Sub-Total			4.00727	100	1000000	5.329226	53292
Total			75.194228			100	1000000

Important Note

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights. See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.